L Number	Hits	Search Text	DB	Time stamp
6	256	(directional adj coupler) and substrate	USPAT;	2003/10/15 18:45
		and transformer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	011	1 12	IBM_TDB	2002/10/15 17.27
7	211	low adj temperature adj cofired adj	USPAT; US-PGPUB;	2003/10/15 17:37
		Ceramic	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	20	(low adj temperature adj cofired adj	USPAT;	2003/10/15 17:40
		ceramic) and transformer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1.0	(1the add substants) and therefores	IBM_TDB USPAT;	2003/10/15 17:43
9	19	(ltcc adj substrate) and transformer	US-PGPUB;	2003/10/13 17.43
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
11	4	resistor with transformer with capacitor	USPĀT;	2003/10/15 17:45
		with vias with substrate	US-PGPUB;	
			EPO; JPO;	
ľ			DERWENT;	
12	39	register same transformer same canaciter	IBM_TDB USPAT;	2003/10/15 17:49
14	39	resistor same transformer same capacitor same vias same substrate	US-PGPUB;	2003/10/13 17:49
		Same vias same substitute	EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	3		USPĀT;	2003/10/15 17:50
		same vias same substrate	US-PGPUB;	
			EPO; JPO;	••
			DERWENT; IBM TDB	
14	138	transformer adj substrate	USPAT;	2003/10/15 17:56
7.4	150	cransformer adj substrace	US-PGPUB;	2003/10/13 17:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	6	transformer adj attached adj substrate	USPAT;	2003/10/15 17:57
		•	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
16	21	transformer adj mounted adj substrate	USPAT;	2003/10/15 17:58
- •			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
17			IBM_TDB	0000/70/75 70 5
17	211	transformer near substrate	USPAT;	2003/10/15 19:34
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
18	512	inductor near substrate	USPAT;	2003/10/15 18:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1.0		(directional add sounlaw) and (himsell	IBM_TDB USPAT;	2003/10/15 18:47
19	6	(directional adj coupler) and (binocular adj core)	US-PGPUB;	2003/10/13 18:4/
		44) 5516/	EPO; JPO;	
			DERWENT;	
i			IBM_TDB	
20	0	(directional adj coupler) and (low adj	USPĀT;	2003/10/15 18:48
		temperature adj cofired adj ceramic adj	US-PGPUB;	
		substrate)	EPO; JPO;	
l			DERWENT; IBM TDB	
	<u> </u>		TDM 1DB	<u> </u>

	,			1
21	1	(directional adj coupler) and (low adj	USPAT;	2003/10/15 18:48
		temperature adj co adj fired adj ceramic adj substrate)	US-PGPUB; EPO; JPO;	
	1	adj subscrace)	DERWENT;	
			IBM TDB	
22	5	(directional adj coupler) and (low adj	USPAT;	2003/10/15 18:50
		temperature adj co adj fired adj ceramic)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	20	/	IBM_TDB USPAT;	2003/10/15 18:50
23	28	(coupler) and (low adj temperature adj co adj fired adj ceramic)	US-PGPUB;	2003/10/13 18:30
		day fired day ceramie,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
24	0	transformer near (reflow adj solder adj	USPAT;	2003/10/15 19:35
		paste)	US-PGPUB;	
	ļ		EPO; JPO; DERWENT;	
			IBM TDB	
25	0	transformer adj (reflow adj solder adj	USPAT;	2003/10/15 19:35
		paste)	US-PGPUB;	
			EPO; JPO;	
]		DERWENT;	
			IBM_TDB	0000/10/15 10.05
26	0	transformer with (reflow adj solder adj paste)	USPAT; US-PGPUB;	2003/10/15 19:35
		pasce,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
27	0	transformer same (reflow adj solder adj	USPAT;	2003/10/15 19:35
		paste)	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT; IBM TDB	•
28	3	transformer and (reflow adj solder adj	USPAT;	2003/10/15 19:55
20		paste)	US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0002/10/15 10 27
29	0	(directional adj coupler) and (reflow adj solder adj paste)	USPAT; US-PGPUB;	2003/10/15 19:37
		Solder adj paste/	EPO; JPO;	
İ			DERWENT;	
			IBM TDB	
30	0	5015972.pn. and resistor	USPAT;	2003/10/15 19:55
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
31	0	5015972.pn. and resistance	USPAT;	2003/10/15 20:15
			US-PGPUB;	
	l		EPO; JPO;	
			DERWENT;	
20		(+	IBM_TDB	2002/10/15 20 13
32	0	(transformer adj attached) near epoxy	USPAT;	2003/10/15 20:17
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
33	0	(transformer adj attached) adj epoxy	USPĀT;	2003/10/15 20:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
34	3	(transformer adj attached) same epoxy	USPAT;	2003/10/15 20:16
		, standiother adjactaoned, band opony	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

			110000	0000/10/15 00 16
35	3	(transformer adj attached) with epoxy	USPAT;	2003/10/15 20:16
			US-PGPUB;	
			EPO; JPO;	
	İ		DERWENT;	
			IBM_TDB	
36	34	(transformer) near epoxy	USPAT;	2003/10/15 20:21
	!		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
37	29	(transformer) adj epoxy	USPAT;	2003/10/15 20:21
		(US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
38	844	(transformer) with epoxy	USPAT;	2003/10/15 20:22
70	044	(Clansformer) with epoxy	US-PGPUB;	2003/10/10 20:22
			EPO; JPO;	
			DERWENT;	
			1	
30	0.0	(turneformer) with open with substrate	IBM_TDB	2003/10/15 20:40
39	26	(transformer) with epoxy with substrate	USPAT;	2003/10/15 20:40
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
40	7	resistor adj overglaze	USPAT;	2003/10/15 20:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
41	2	(resistor adj overglaze) and (coupler or	USPAT;	2003/10/15 20:41
		transformer)	US-PGPUB;	
		·	EPO; JPO;	.
			DERWENT;	
			IBM TDB	
42	6	(directional adj coupler) and (binocular	USPAT;	2003/10/15 20:59
	1	adj core)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
43	1047	(directional adj coupler) and transformer	USPAT;	2003/10/15 20:47
43	104/	(directional adj couple) and transformer	US-PGPUB;	2003/10/13 20:4/
			EPO; JPO;	
			DERWENT;	
1	2001	222/6 1 1	IBM_TDB	2002/10/15 21 21
44	3031	333/\$.ccls. and coupler	USPAT;	2003/10/15 21:01
1			US-PGPUB;	
1			EPO; JPO;	[
1			DERWENT;	
1			IBM_TDB	
45	512	333/\$.ccls. and coupler and transformer	USPAT;	2003/10/15 21:01
!			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	ĺ
			IBM TDB	
	l	L		